Sprint

Letter of Commitment for the Sprint Candidate for Chair of 3GPP RAN5
Mr. Nick Baustert

To: Mobile Competence Center
Attn: Ingbert Sigovich and Susanna Kooistra

Sprint is pleased to nominate Mr. Nick Baustert as a candidate for the Chair of the 3GPP RAN5 working group.

Nick has over 23 years of experience in the design, test, certification and production of wireless devices. In his 15 years with Sprint he has held engineering and management positions, all relating to the development and commercialization of wireless devices and services. Mr. Baustert currently serves as Chair of the Board of Directors for the Global Certification Forum (GCF) and CDMA Certification Forum (CCF). He is also very engaged in the efforts to harmonize the CCF and GCF Certification programs, thereby making it easier for existing CDMA operators to adopt 3GPP/GCF practices for certification.

Sprint is in the process of deploying an FDD LTE system that will cover 250 million POPS by the end of 2013 and has recently acquired the remaining interests of Clearwire, a major North American TD-LTE operator. Sprint is uniquely qualified to understand the needs of the LTE FDD and TDD operators and equipment manufacturers. Nick will ensure that RAN5 champions the needs of both TDD and FDD.

Mr. Baustert represents Sprint in 3GPP as a member of ETSI.

Sprint is fully committed to support Mr. Baustert in his task as a Chair. Attached is a copy of Mr. Baustert's Curriculum Vitae.

Sincerely,

Mark Lipford
Director – Global Standards and Ecosystem Development
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Nick J. Baustert   7527 W 140th Street #1303
                                                                                                      Overland Park, KS 66223

Work Experience

Sprint

Research Scientist/Manager, Global Standards   January 2006 to Present
RAN Development and Device Certification
- Responsible for development of Device specifications and industry test processes in CDG, CCF, GSMA, GCF, GTI
- Led the standards team responsible for all air interface work in 3GPP2, 3GPP, and IEEE, and Wi-Fi Alliance

Customer Equipment Certification   October 1997 to January 2006
Manager, Test Development
- Involved in virtually every wireless device technology launched since SMS, and led the   test design and development for the first 3G/cdma2000 deployment in the US.
- Managed staffs ranging from 5 to 15 direct reports.
- Managed budgets and development projects ranging up to $4,000,000
- Managed teams and/or directly contributed in various industry groups including; WAP Forum/OMA, OTAFF, CDG, CTIA, ATIS, WiMax Forum, CCF, and the FCC

AeroComm Wireless, Inc.   December 1994 to June 1997
- Worked in the design and development of radio frequency data communications products operating in the 2.4GHz band. Design experience with both direct sequence and frequency hopping spread spectrum radios.
- Led international regulatory compliance work with radio approvals in Europe and Japan.
- Hired, trained and supervised the production, test, shipping and customer support staff and managed the production of over 20,000 wireless printer sharing devices.

Garmin International   July 1990 to December 1994
- Helped design and develop industry leading Global Positioning System technology. Including satellite receivers, base band processors and embedded CPU systems in hand-held and panel mount navigation systems.
- Responsible for several domestic and international EMI/RFI and radio type approvals for aviation and marine electronic systems.
- Trained and supported production staff in the US, Taiwan, and United Kingdom.

Education: DeVry Institute of Technology, Kansas City, Missouri
          Graduation Date: February 24, 1989
          GPA 3.65/4.00 (Dean's list, Presidential Honor Society)
          Graduate of Focus Seminars of Kansas City

Experience with: Frequency hopping and direct sequence spread spectrum systems, FSK, PSK & BPSK modulation, microwave mixers and filters, RF power amps, MMIC's, PLL's, microwave transmission lines and impedance matching, Base band processing, FPGA's, embedded μProcessor systems, various display technologies, series pass and switching power supplies, flash and EEPROM memories,

References available upon request